

TQP3M9006

High Linearity LNA Gain Block

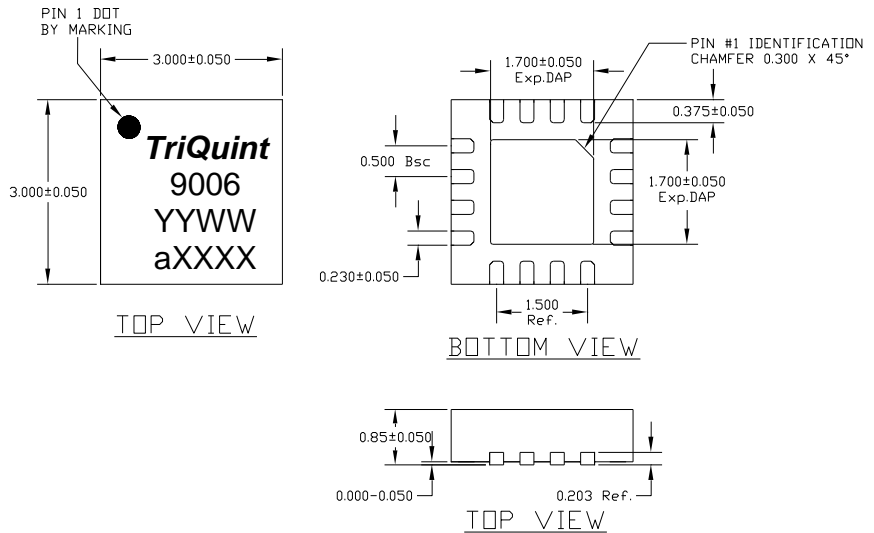


Mechanical Information

Package Information and Dimensions

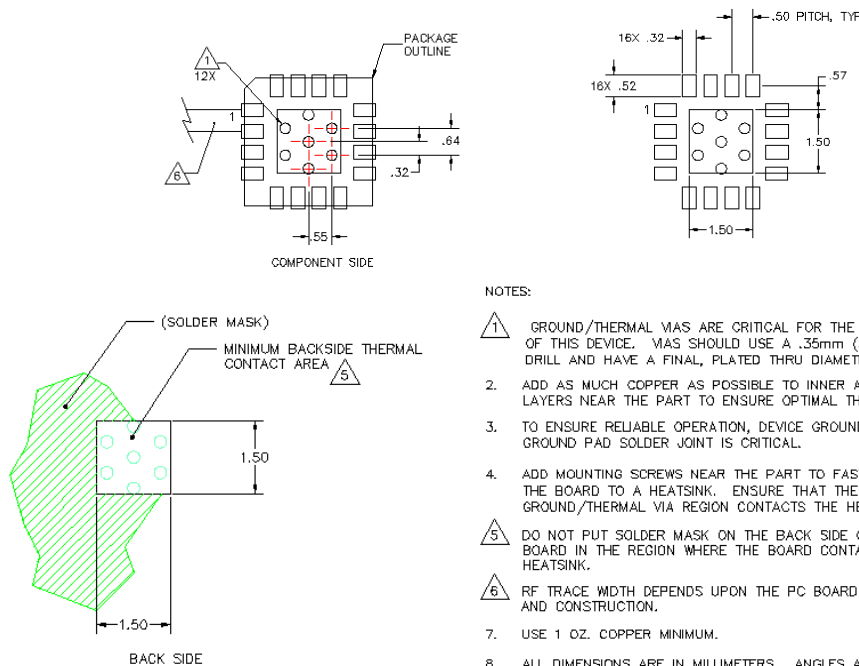
This package is lead-free/RoHS-compliant. The plating material on the leads is annealed matte tin. It is compatible with both lead-free (maximum 260 °C reflow temperature) and lead (maximum 245 °C reflow temperature) soldering processes.

The component will be marked with a “9006” designator with an alphanumeric lot code on the top surface of package.



Mounting Configuration

All dimensions are in millimeters (inches). Angles are in degrees.



Notes:

- Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.